



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

27-AUG-2003

SUBJECT: ON Semiconductor Final Product/Process Change Notification #13024

TITLE: Assembly/Test Site Capacity Addition for Clock and Data Management Products in the 8 Lead SOIC Narrow Body Package

EFFECTIVE DATE: 27-Oct-2003

AFFECTED CHANGE CATEGORY: On Semiconductor Assembly/Test Site

AFFECTED PRODUCT DIVISION:

Broadband Products Div
Analog Products Div

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Keith Stapley <RXNN90@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Prescott Sakai <FFNWHF@onsemi.com>

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or John Veto <RRTD61@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

ON Semiconductor is pleased to announce that it has successfully completed qualification of the ON Semiconductor Philippines Incorporated (OSPI) facility located in Carmona, Philippines to assemble and test the listed Clock and Data Management products in 8 lead narrow body SOIC packages. This FPCN is in addition to devices qualified under FPCN 11507 located at www.onsemi.com. OSPI is a TS16949 and ISO9001:2000 certified facility. ON Semiconductor's OSPI facility has been producing high quality SOIC, TSSOP and PLCC products for over 10 years.

Currently the listed devices are manufactured and tested at Advanced Semiconductor Engineering (ASE-CL) in ChungLi, Taiwan.

There will be no changes in device functionality. Reliability will continue to meet or exceed ON Semiconductor's highest standards.



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RELIABILITY DATA SUMMARY:

Test	Conditions	Results
High Temp Op Life (HTOL)	Tj =150DegC for 1512 hours	0/316
High Temp Bake (HTB)	150DegC for 1008 hours 175DegC for 504 hours	0/317 0/240
Preconditioning for MSL-1 (PC)	IR at 235DegC IR at 260DegC	0/231 0/480
PC-HAST	130DegC/85% RH/18.8 PSIG for 96 hours	0/313
PC-Autoclave (AC)	121DegC/100% RH/15 PSIG for 192 hours	0/317
PC-Temp Cycling (TC)	-65DegC to +150DegC; for 1000 cycles	0/316
ESD per JEDEC Standard	Human Body Model(HBM) Machine Model (MM) Charge Device Model(CDM)	MEETS OR EXCEEDS CRITERIA
Construction Analysis (CA)	TACL Report LIMS# 6270A	COMPLETE
Parameter Verification	Electrical Characterization/distribution summary of CriticalParameters	AVAIL

Qualification Vehicle Justification

Technology	Qualification Device	Reason Chosen
MOSAIC35	MC10EL16D	Smallest array, high volume, 8ld SOIC

ELECTRICAL CHARACTERISTIC SUMMARY:

Data is available upon request. No changes in device functionality occurred. Device parameters will continue to meet all data book specifications.

CHANGED PART IDENTIFICATION:

Parts manufactured in OSP1 will be marked with a "P" in their trace code (example: PLZN).

AFFECTED DEVICE LIST (WITHOUT SPECIALS):

- PART**
- MC100EP01D
- MC100EP01DR2
- MC100EP05D
- MC100EP05DR2
- MC100EP08D
- MC100EP08DR2
- MC100EP11D
- MC100EP11DR2
- MC100EP140D
- MC100EP140DR2
- MC100EP16D
- MC100EP16DR2



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MC100EP16FD
MC100EP16FDR2
MC100EP16TD
MC100EP16TDR2
MC100EP16VAD
MC100EP16VADR2
MC100EP16VBD
MC100EP16VBDR2
MC100EP16VCD
MC100EP16VCDR2
MC100EP16VSD
MC100EP16VSDR2
MC100EP16VTD
MC100EP16VTDR2
MC100EP31D
MC100EP31DR2
MC100EP32D
MC100EP32DR2
MC100EP33D
MC100EP33DR2
MC100EP35D
MC100EP35DR2
MC100EP51D
MC100EP51DR2
MC100EP52D
MC100EP52DR2
MC100EP58D
MC100EP58DR2
MC100EPT20D
MC100EPT20DR2
MC100EPT21D
MC100EPT21DR2
MC100EPT22D
MC100EPT22DR2
MC100EPT23D
MC100EPT23DR2
MC100EPT24D
MC100EPT24DR2
MC100EPT25D
MC100EPT25DR2
MC100EPT26D
MC100EPT26DR2
MC100LVELT23D
MC100LVELT23DR2
MC100LVEP11D
MC100LVEP11DR2
MC100LVEP16D
MC100LVEP16DR2
MC10EP01D
MC10EP01DR2
MC10EP05D
MC10EP05DR2
MC10EP08D
MC10EP08DR2
MC10EP11D
MC10EP11DR2



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MC10EP16D
MC10EP16DR2
MC10EP16TD
MC10EP16TDR2
MC10EP16VAD
MC10EP16VADR2
MC10EP31D
MC10EP31DR2
MC10EP32D
MC10EP32DR2
MC10EP33D
MC10EP33DR2
MC10EP35D
MC10EP35DR2
MC10EP51D
MC10EP51DR2
MC10EP52D
MC10EP52DR2
MC10EP58D
MC10EP58DR2
MC10EP89D
MC10EP89DR2
MC10EPT20D
MC10EPT20DR2
MC10LVEP11D
MC10LVEP11DR2
MC10LVEP16D
MC10LVEP16DR2
MC12026AD
MC12026ADR2
MC12080D
MC12080DR2
MC12093D
MC12093DR2
MC12095D
MC12095DR2
MCH12140D
MCH12140DR2
MCK12140D
MCK12140DR2
NB100ELT23LD
NB100ELT23LDR2